L	Hits	Search Text	DB	Time stamp
Number 1	F.C.2	1420 (660) 027 2		
1	582	(438/660).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/27 15:49
2	162	(438/663).ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/27 15:49
-	25	"single wafer" same (rtp or rapid adj thermal) and convection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/05 10:22
-	31	thermal and susceptor and gas adj ring and quartz	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/05 09:57
-	271	(rtp or rapid adj thermal) and convection and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/05 11:49
~	2	("5879459").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/05
_	14	["4533410"   "4533820"   "4689247"   "4888224"   "4881338"   "4846102"   "4976996"   "4993360"   "5077875"   "5119760"   "5194401"   "5336327"   "5749974"   "5788447").PN.	USPĀT	2003/06/05
-	20	5879459.URPN.	USPAT	2003/06/05
-	0	(21/5).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/05
-	0	(21/6).ccLs.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/05
-	0	(21/7).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/05 10:27
-	46	(rtp or rapid adj thermal) and convection and wafer and rotate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/05 11:50
-		5837555.URPN.	USPĀT	2003/10/25 13:03
-	7	("3713900"   "4312681"   "4365588"   "4794217"   "4978567"   "5011794"   "5308161").PN.	USPAT	2003/10/25 13:05
-	8	4365588.URPN.	USPAT	2003/10/25 13:06